

ECE 4813

Semiconductor Device and Material Characterization

Dr. Alan Doolittle School of Electrical and Computer Engineering Georgia Institute of Technology

As with all of these lecture slides, I am indebted to Dr. Dieter Schroder from Arizona State University for his generous contributions and freely given resources. Most of (>80%) the figures/slides in this lecture came from Dieter. Some of these figures are copyrighted and can be found within the class text, *Semiconductor Device and Materials Characterization*. <u>Every serious</u> *microelectronics student should have a copy of this book!*



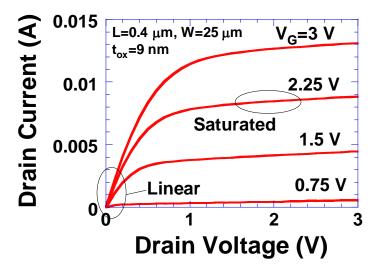
MOSFETS

Effective Channel Length Threshold Voltage



Drain Current – Drain Voltage

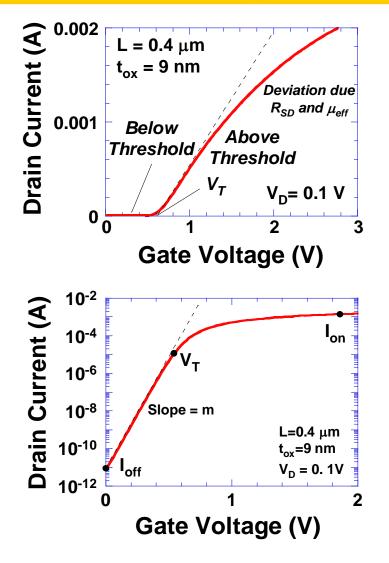
- Linear at low V_D
- Saturated at high V_D
- Device parameters determined at low V_D
 - igodoldrightarrow Drain conductance g_d
 - Effective channel length L_{eff}
 - Effective channel width W_{eff}
 - Source/drain resistance R_{SD}
 - Effective mobility μ_{eff}





Drain Current – Gate Voltage

- Linear at low V_D low V_G ($V_D = 0.1$ V)
- Nonlinear at higher V_G
- Two regions
 - Above threshold voltage
 - Below threshold voltage (subthreshold)
- Device parameters
 - Threshold voltage V_{τ}
 - Transconductance g_m
 - Field-effect mobility μ_{FE}

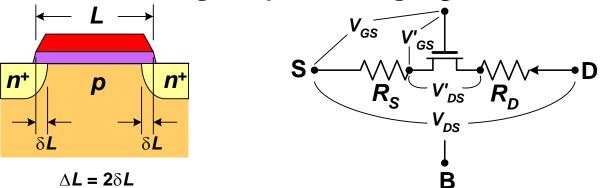






MOSFET Current-Voltage

- Series resistance degrades the MOSFET current
- δL results from self aligned processing G



$$\Delta L = 2 \delta L$$

$$I_{D} = k (V_{GS} - V_{T} - 0.5 V_{DS}) V_{DS}$$
$$I_{D} = k [(V_{GS} - I_{D}R_{S}) - V_{T} - 0.5 (V_{DS} - I_{D}R_{SD})] (V_{DS} - I_{D}R_{SD})$$
$$= k (V_{GS} - V_{T} - 0.5 V_{DS}) (V_{DS} - I_{D}R_{SD})$$

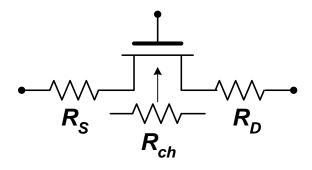
For $(V_{GS}-V_T) >> 0.5V_{DS}$,

$$\boldsymbol{I}_{D} = \frac{\boldsymbol{W}_{eff} \boldsymbol{\mu}_{eff} \boldsymbol{C}_{ox} (\boldsymbol{V}_{GS} - \boldsymbol{V}_{T}) \boldsymbol{V}_{DS}}{(\boldsymbol{L} - \Delta \boldsymbol{L}) + \boldsymbol{W}_{eff} \boldsymbol{\mu}_{eff} \boldsymbol{C}_{ox} (\boldsymbol{V}_{GS} - \boldsymbol{V}_{T}) \boldsymbol{R}_{SD}}$$



MOSFET Resistance

• The MOSFET resistance is due to the channel resistance, R_{ch} , and the source/drain resistance, $R_{SD} = R_S + R_D$

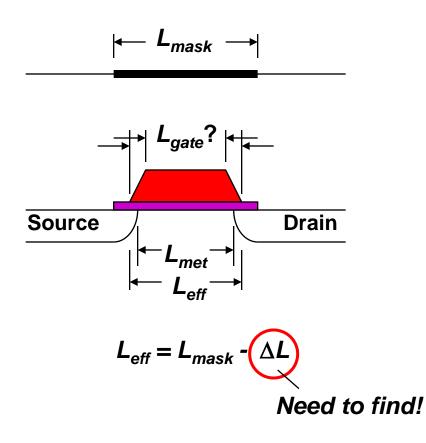


$$\boldsymbol{R}_{m} = \boldsymbol{R}_{ch} + \boldsymbol{R}_{SD} = \frac{\boldsymbol{L} - \Delta \boldsymbol{L}}{\boldsymbol{W}_{eff} \boldsymbol{\mu}_{eff} \boldsymbol{C}_{ox} (\boldsymbol{V}_{GS} - \boldsymbol{V}_{T})} + \boldsymbol{R}_{SD}$$



Channel Length

What is channel length?



- L_{mask}: design length on mask
 - 🔶 (well known)
- L_{gate}: actual gate length
 - (measured by e.g., SEM)
- *L_{met}*: distance between metallurgical junctions (difficult to measure)
- *L_{eff}*: not well defined; result of an electrical measurement (important for modeling purposes)



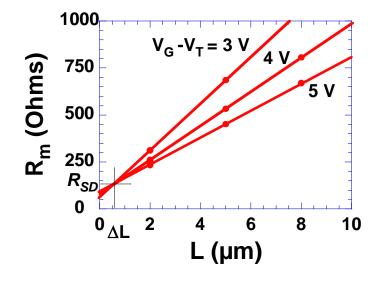


Effective Channel Length

- Need several MOSFETs with different channel lengths
- Plot R_M versus L
- L is mask-defined channel length

$$\boldsymbol{R}_{m} = \frac{\boldsymbol{L} - \Delta \boldsymbol{L}}{\boldsymbol{W}_{eff} \boldsymbol{\mu}_{eff} \boldsymbol{C}_{ox} (\boldsymbol{V}_{G} - \boldsymbol{V}_{T})} + \boldsymbol{R}_{SD}$$

Equation converges to R_{SD} when numerator is zero \rightarrow results in ΔL determined at RSD



Important Note: you need to measure V_{T} of each device separately, since MOSFETs with different channel lengths have different threshold voltages!

Advanced Semiconductor Technology Facility



Effective Channel Length

$$R_{m} = \frac{L - \Delta L}{W_{eff} \mu_{eff} C_{ox} (V_{G} - V_{T})} + R_{SD}$$

$$R_{m} (V_{G} - V_{T}) = \frac{L - \Delta L}{W_{eff} \mu_{eff} C_{ox}} + R_{SD} (V_{G} - V_{T})$$

$$R_{m} (V_{G} - V_{T}) = \frac{L - \Delta L}{W_{eff} \left(\frac{\mu_{o}}{1 + \theta(V_{GS} - V_{T})}\right)} C_{ox}$$

$$R_{m} (V_{G} - V_{T}) = \frac{(L - \Delta L)(1 + \theta(V_{GS} - V_{T}))}{W_{eff} \mu_{o} C_{ox}} + R_{SD} (V_{G} - V_{T})$$

$$R_{m} (V_{G} - V_{T}) = \left[\frac{(L - \Delta L)}{W_{eff} \mu_{o} C_{ox}} \theta + R_{SD}\right] (V_{GS} - V_{T}) + \left\{\frac{(L - \Delta L)}{W_{eff} \mu_{o} C_{ox}}\right\}$$

Allows ΔL , R_{SD} , μ_o , and θ to be determined...

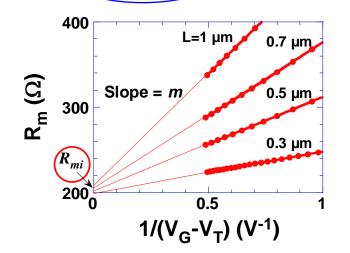
$$R_{m} = \left[\frac{\left(L - \Delta L\right)}{W_{eff} \,\mu_{o} C_{ox}} \theta + R_{SD}\right] + \left\{\frac{\left(L - \Delta L\right)}{W_{eff} \,\mu_{o} C_{ox}}\right\} \frac{1}{\left(V_{GS} - V_{T}\right)}$$

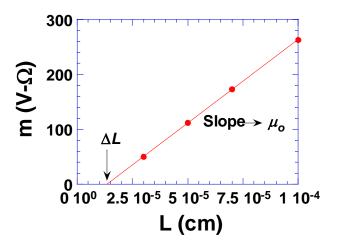


Effective Channel Length

- Allows ΔL , R_{SD} , μ_o , and θ to be determined
- A) Plot R_m vs 1/(V_{GS}-V_T)
- Determine slope, m, and intercept R_{mi}
 - B) Plot m= 1/($W_{eff}\mu_o C_{ox}$) vs L \rightarrow gives μ_o and ΔL

$$\boldsymbol{R}_{m} = \frac{\boldsymbol{L} - \Delta \boldsymbol{L}}{\boldsymbol{W}_{eff} \boldsymbol{\mu}_{o} \boldsymbol{C}_{ox} (\boldsymbol{V}_{G} - \boldsymbol{V}_{T})} + \frac{\boldsymbol{\theta} (\boldsymbol{L} - \Delta \boldsymbol{L})}{\boldsymbol{W}_{eff} \boldsymbol{\mu}_{o} \boldsymbol{C}_{ox}} + \boldsymbol{R}_{SD}$$



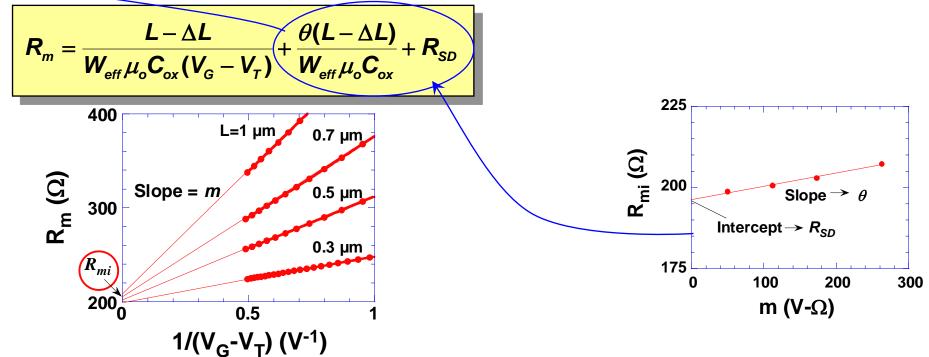




Effective Channel Length

- Allows ΔL , R_{SD} , μ_o , and θ to be determined
- A) Plot R_m vs 1/(V_{GS}-V_T)
- Determine intercept R_{mi}

C) Plot R_{mi} vs m= 1/($W_{eff}\mu_{o}C_{ox}$) \rightarrow gives θ and R_{sD}



F.H. de la Moneda et al. "Measurement of MOSFET Constants," IEEE Electron Dev. Lett. EDL-3, 10-12, Jan. 1982.



Shift and Ratio Method

Uses one large and several variable-L devices

$$\boldsymbol{R}_{m} = \frac{\boldsymbol{L} - \Delta \boldsymbol{L}}{\boldsymbol{W}_{\text{eff}} \boldsymbol{\mu}_{\text{eff}} \boldsymbol{C}_{\text{ox}} (\boldsymbol{V}_{\text{G}} - \boldsymbol{V}_{\text{T}})} + \boldsymbol{R}_{\text{SD}}$$

Measure resistance R_m

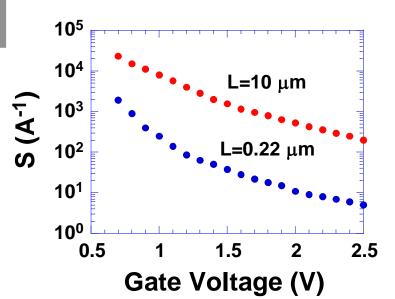
$$R_{m} = R_{SD} + L_{eff} f(V_{G} - V_{T})$$

f is a general function of gate overdrive,
 $V_{G} - V_{T}$

$$\mathbf{S} = \frac{dR_m}{dV_G} = L_{eff} \frac{d[f(V_G - V_T)]}{dV_G}$$

- Plot S versus V_G for large and one small device
- Determine ratio r

$$\frac{S_{Long}(V_G)}{S_{Short}(V_G + \Delta V_T)} = \frac{L_{Long} - \Delta L}{L_{Short} - \Delta L} = r$$



Ratio is not constant with gate voltage ONLY due to differences in threshold voltage.



Shift and Ratio Method

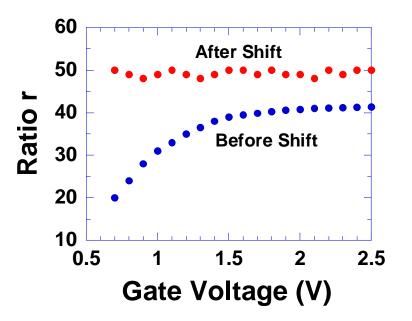
- Shift one curve horizontally by ΔV_T (threshold voltage difference between the two devices) until *r* becomes constant
- The key is to find ΔV_T for which *r* is constant
- **Determine** ΔL and L_{eff}

$$\Delta L = \frac{L_{Long} - rL_{Short}}{r - 1}$$

Once ∆L is found, RSD can be found from:

$$\boldsymbol{R}_{m} = \frac{\boldsymbol{L} - \Delta \boldsymbol{L}}{\boldsymbol{W}_{eff} \boldsymbol{\mu}_{eff} \boldsymbol{C}_{ox} (\boldsymbol{V}_{G} - \boldsymbol{V}_{T})} + \boldsymbol{R}_{SD}$$

Y. Taur, "MOSFET Channel Length: Extraction and Interpretation," IEEE Trans. Electron Dev. 47, 160-170, Jan. 2000.





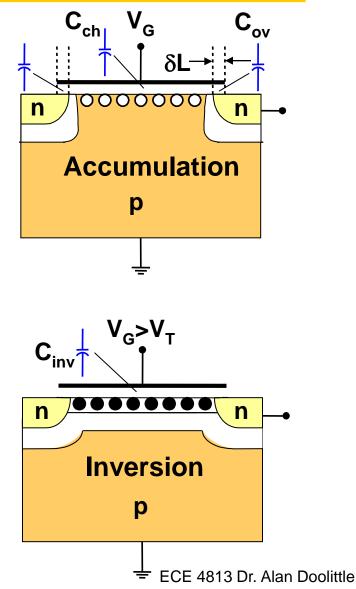
Capacitance Effective Channel Length

- Capacitance measured between G and S/D
- Step A) MOSFET biased into accumulation; source connected to drain
- Measure C = 2C_{ov}; C_{ch} ~0 (shunted to ground)
- Step B) MOSFET biased into inversion; source connected to drain

• Measure
$$C_{inv} = 2C_{ov} + C_{ch}$$

$$C_{inv} = \frac{K_{ox}\varepsilon_{0}LW}{t_{ox}}; \quad C_{ov} = \frac{K_{ox}\varepsilon_{0}\delta LW}{t_{ox}}$$
$$L_{met} = L\left(1 - \frac{2C_{ov}}{C_{inv}}\right)$$

Note missing factor of 2 in text.

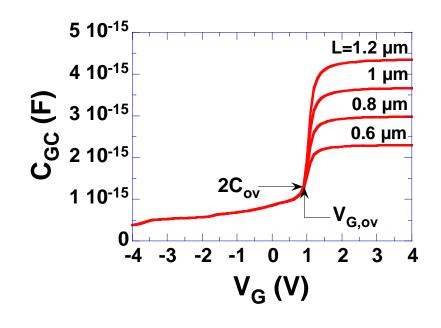






Capacitance Effective Channel Length

- Due to extremely small device size, in modern MOSFETs, you need many device connected in parallel
- Not influenced by series resistance





Threshold Voltage

Threshold voltage is an important MOSFET parameter

$$V_{T} = V_{FB} + 2\phi_{F} + \frac{\sqrt{2qK_{s}\varepsilon_{0}N_{A}(2\phi_{F} - V_{BS})}}{C_{ox}}$$

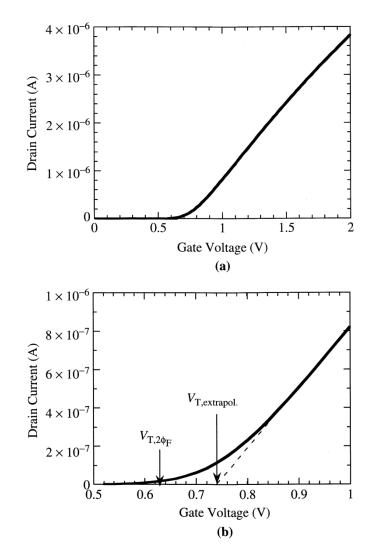
$$V_{FB} = \phi_{MS} - \frac{Q_f}{C_{ox}} - \gamma \frac{Q_m}{C_{ox}} - \gamma \frac{Q_{ot}}{C_{ox}} - \frac{Q_{it}(\phi_S)}{C_{ox}}$$

- V_T depends on
 - Oxide thickness
 - Doping density
 - Work function difference
 - Oxide charge
 - Interface trap charge
 - Substrate voltage



Threshold Voltage

There is no unique definition of the threshold voltage



$$V_{T,2\phi_F} = V_{FB} + 2\phi_F + \frac{\sqrt{2qK_s\varepsilon_0N_A(2\phi_F - V_{BS})}}{C_{ox}}$$
$$V_{FB} = \phi_{MS} - \frac{Q_f}{C_{ox}} - \gamma \frac{Q_m}{C_{ox}} - \gamma \frac{Q_{ot}}{C_{ox}} - \frac{Q_{it}(\phi_S)}{C_{ox}}$$

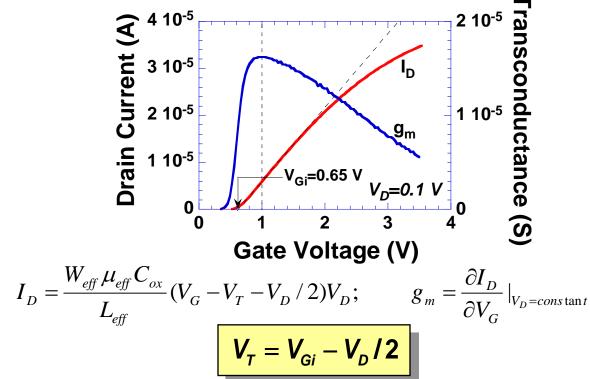
$$\phi_{Surface} = 2\phi_F = \frac{2kT}{q} \ln\left(\frac{p}{n_i}\right) \approx \frac{2kT}{q} \ln\left(\frac{N_A}{n_i}\right)$$

Advanced Semiconductor Technology Facility



Threshold Voltage: Linear Extrapolation

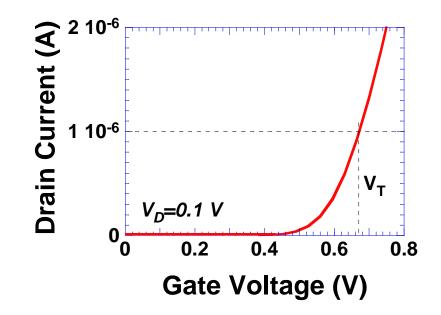
- Since the drain current is not actually equal zero below threshold, there is no "threshold voltage" where the Drain current =0. Otherwise, ID would =0 at V_T=V_{GS}+0.5V_{DS}
- Solution: Use asymptotic V_{GS(intercept)}
- Measure I_D-V_G; find point of maximum slope (g_{m,max}); fit straight line, intercept on V_G axis is V_{Gi}





Threshold Voltage: Constant Normalized Drain Current

- *I_D* extrapolation is time consuming; faster method is to measure *V_G* at "some" low *I_D* where *I_D* is normalized to the device geometry
- $V_T = V_G$ at $I_T = I_{DO} / (W/L)$ with $I_{DO} \approx 50-100$ nA

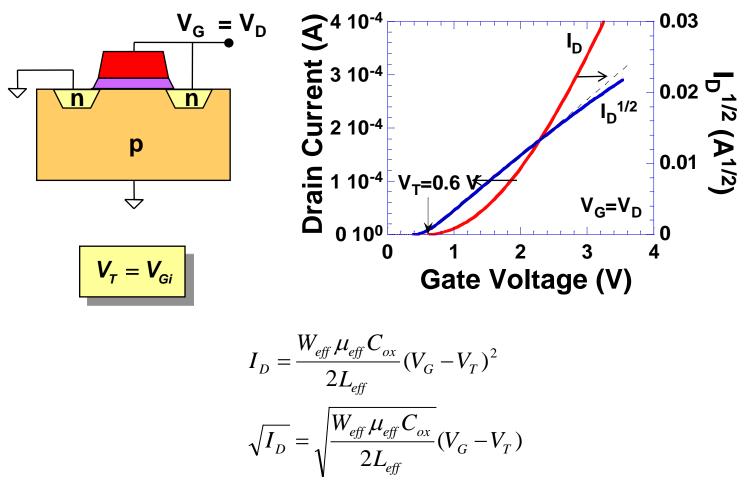


Advanced Semiconductor Technology Facility 🛁



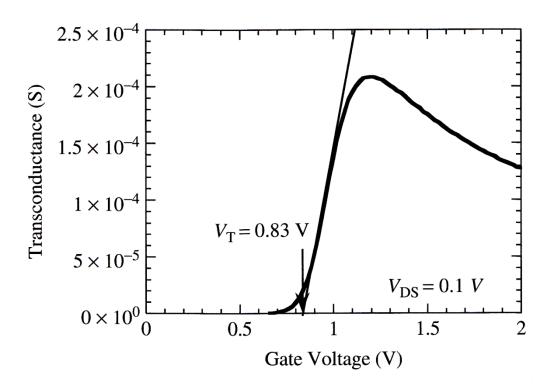
Threshold Voltage: Saturation

• Measure $I_D - V_G$; plot $I_D^{1/2} - V_G$, extrapolated intercept is V_G



Threshold Voltage: Transconductance Slope

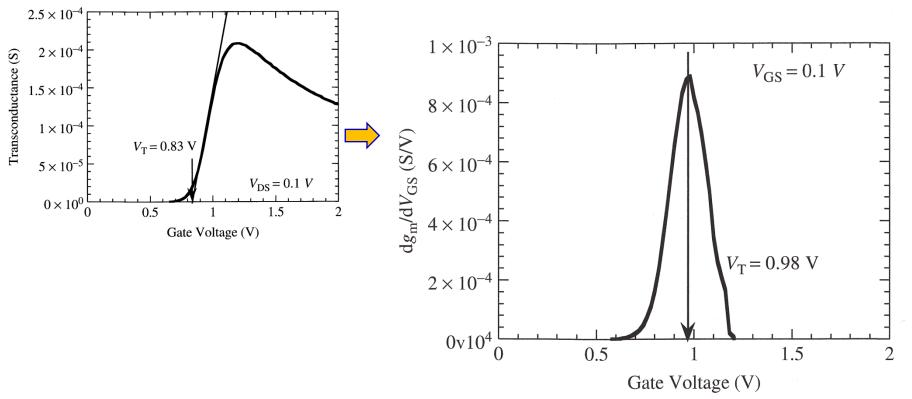
- Measure $g_m V_G$
- V_T, is the intercept extrapolated from the maximum slope (1st derivative)



Advanced Semiconductor Technology Facility 🛁

Threshold Voltage: Transconductance

- Commonly used in RF devices (and others) since small signal parameters are often measured
- Measure $g_m V_G$
 - Plot dg_m/dV_{GS} and V_T is the maximum of the (1st derivative)



ECE 4813 Dr. Alan Doolittle



Review Questions

- How is the threshold voltage measured?
- Name three device/material parameters that influence V_T.
- Why does the effective channel length differ from the physical gate length?
- What is an advantage of the capacitance technique over current-voltage techniques for effective channel length determination?